

April 16 (Tue.)	April 17 (Wed.)	April 18 (Thu.)
9:00 - 9:10 Opening		
<p>9:10 - 10:10 <u>Session 1</u> Opening Session Day1</p> <p>Keynote Presenter: Xin Wu (Xilinx, Inc.)</p> <p>Invited Talk Presenter: Yasumitsu Orii (NAGASE & CO., LTD.)</p>	<p>9:00 - 10:30 <u>Session 6</u> Opening Session Day2</p> <p>Keynote Presenter: Atsuyoshi Koike (Western Digital Corporation)</p> <p>Invited Talk Presenter: Aki Fujimura (D2S, Inc.)</p> <p>Invited Talk Presenter: Kazutoshi Wakabayashi (NEC Corporation)</p>	<p>9:00 - 10:00 <u>Session 11</u> Opening Session Day3</p> <p>Invited Talk Presenter: Seiji Nagahara (Tokyo Electron Ltd.)</p> <p>Invited Talk (BACUS 2018 Best Paper) Presenter: Vicky Philipsen (imec)</p>
10:10 - 10:30 Break		10:00 - 10:20 Break
<p>10:30 - 11:50 <u>Session 2</u> Litho & Etching</p>	10:30 - 10:50 Break	<p>10:20 - 11:40 <u>Session 12</u> EUVL III</p>
11:50 - 13:20 Lunch Break	10:50 - 12:10 Session 7 EDA & MDP	11:40 - 13:10 Lunch Break
<p>13:20 - 14:30 <u>Session 3</u> FPD</p> <p>Invited Talk Presenter: Kouichi Murakami (FSCE Inc.)</p>	12:10 - 13:40 Lunch Break	<p>13:10 - 15:00 <u>Session 13</u> NIL</p> <p>Invited Talk Presenter: Tatsuhiko Higashiki (Toshiba Memory Corporation)</p>
14:30 - 14:50 Break	<p>13:40 - 14:40 <u>Session 8</u> Special Session (MEMS & PUF)</p> <p>Invited Talk Presenter: Masayoshi Esashi (Tohoku University)</p> <p>Invited Talk Presenter: Takeshi Fujino (Ritsumeikan University)</p>	15:00 - 15:20 Break
<p>14:50 - 16:10 <u>Session 4</u> Writing & Metrology</p> <p>Invited Talk Presenter: Elmar Platzgummer (IMS Nanofabrication GmbH)</p> <p>Invited Talk (EMLC 2018 Best Paper) Presenter: Klaus-Dieter Roeth (KLA Corporation)</p>	14:40 - 15:00 Break	<p>15:20 - 16:20 <u>Session 14</u> CD & Defect Control</p>
16:10 - 16:30 Break	<p>15:00 - 16:50 <u>Session 9</u> EUVL II</p> <p>Invited Talk Presenter: Moshe Preil (KLA Corporation)</p>	16:20 - 16:40 Break
<p>16:30 - 18:00 <u>Session 5</u> EUVL I</p> <p>Invited Talk Presenter: Jan van Schoot (ASML Netherlands B.V.)</p>	16:50 - 18:20 Session 10 Poster Session	<p>16:40 - 18:20 Panel Discussion</p>
	<p>10A: Process & Material 10B: EUVL Masks 10C: EDA&MDP 10D: Mask Overlay 10E: Fab Management 10S: Mask/Lithography Related Technologies in Academia</p>	
	18:20 - 20:20 Banquet	18:20 - 18:30 Closing